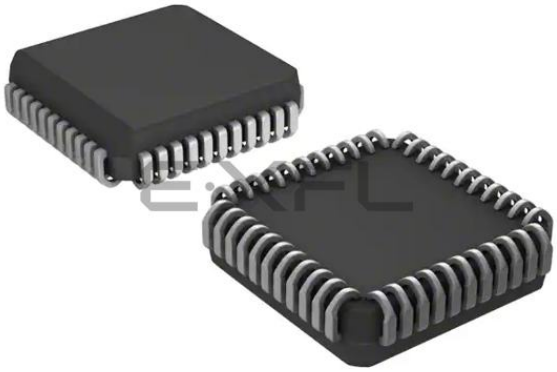

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	16MHz
Connectivity	UART/USART
Peripherals	POR
Number of I/O	32
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/p80c32sbaa-512

80C51 8-bit microcontroller family
128/256 byte RAM ROMless low voltage (2.7V–5.5V), low power, high speed (33 MHz)

80C31/80C32

DESCRIPTION

The Philips 80C31/32 is a high-performance static 80C51 design fabricated with Philips high-density CMOS technology with operation from 2.7 V to 5.5 V.

The 80C31/32 ROMless devices contain a 128 × 8 RAM/256 × 8 RAM, 32 I/O lines, three 16-bit counter/timers, a six-source, four-priority level nested interrupt structure, a serial I/O port for either multi-processor communications, I/O expansion or full duplex UART, and on-chip oscillator and clock circuits.

In addition, the device is a low power static design which offers a wide range of operating frequencies down to zero. Two software selectable modes of power reduction—idle mode and power-down mode are available. The idle mode freezes the CPU while allowing the RAM, timers, serial port, and interrupt system to continue functioning. The power-down mode saves the RAM contents but freezes the oscillator, causing all other chip functions to be inoperative. Since the design is static, the clock can be stopped without loss of user data and then the execution resumed from the point the clock was stopped.

SELECTION TABLE

For applications requiring more ROM and RAM, see the 8XC54/58 and 8XC51RA+/RB+/RC+/80C51RA+ data sheet.

ROM/EPROM Memory Size (X by 8)	RAM Size (X by 8)	Programmable Timer Counter (PCA)	Hardware Watch Dog Timer
80C31/8XC51			
0K/4K	128	No	No
80C32/8XC52/54/58			
0K/8K/16K/32K	256	No	No
80C51RA+/8XC51RA+/RB+/RC+			
0K/8K/16K/32K	512	Yes	Yes
8XC51RD+			
64K	1024	Yes	Yes

FEATURES

- 8051 Central Processing Unit
  - 128 × 8 RAM (80C31)
  - 256 × 8 RAM (80C32)
  - Three 16-bit counter/timers
  - Boolean processor
  - Full static operation
  - Low voltage (2.7 V to 5.5 V@ 16 MHz) operation
- Memory addressing capability
  - 64k ROM and 64k RAM
- Power control modes:
  - Clock can be stopped and resumed
  - Idle mode
  - Power-down mode
- CMOS and TTL compatible
- TWO speed ranges at V_{CC} = 5 V
  - 0 to 16 MHz
  - 0 to 33 MHz
- Three package styles
- Extended temperature ranges
- Dual Data Pointers
- 4 level priority interrupt
- 6 interrupt sources
- Four 8-bit I/O ports
- Full–duplex enhanced UART
  - Framing error detection
  - Automatic address recognition
- Programmable clock out
- Asynchronous port reset
- Low EMI (inhibit ALE)
- Wake-up from Power Down by an external interrupt

80C51/87C51 AND 80C31 ORDERING INFORMATION

ROMless	TEMPERATURE RANGE °C AND PACKAGE	VOLTAGE RANGE	FREQ. (MHz)	DRAWING NUMBER
P80C31SBPN	0 to +70, Plastic Dual In-line Package	2.7 V to 5.5 V	0 to 16	SOT129-1
P80C31SBAA	0 to +70, Plastic Leaded Chip Carrier	2.7 V to 5.5 V	0 to 16	SOT187-2
P80C31SBBB	0 to +70, Plastic Quad Flat Pack	2.7 V to 5.5 V	0 to 16	SOT307-2
P80C31SFPN	–40 to +85, Plastic Dual In-line Package	2.7 V to 5.5 V	0 to 16	SOT129-1
P80C31SFAA	–40 to +85, Plastic Leaded Chip Carrier	2.7 V to 5.5 V	0 to 16	SOT187-2
P80C31SFBB	–40 to +85, Plastic Quad Flat Pack	2.7 V to 5.5 V	0 to 16	SOT307-2

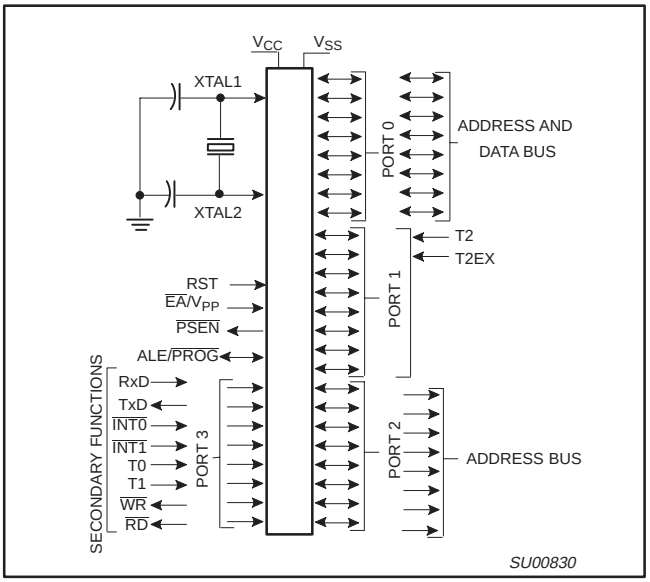
PART NUMBER DERIVATION

DEVICE NUMBER	OPERATING FREQUENCY, MAX (S)	TEMPERATURE RANGE (B)	PACKAGE (AA)
P80C31	S = 16 MHz	B = 0° to +70°C	AA = PLCC
P80C32	U = 33 MHz	F = –40°C to +85°C	BB = PQFP
			PN = PDIP

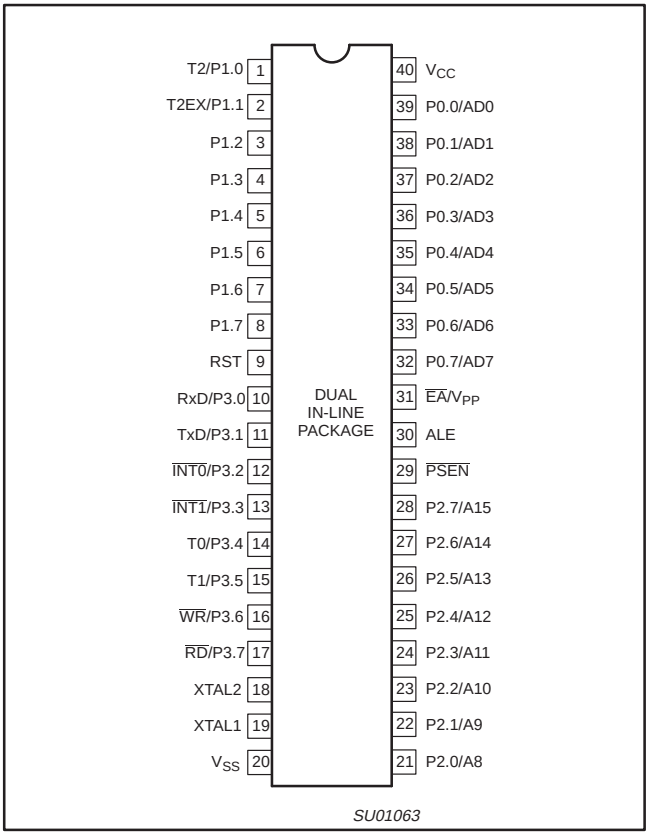
80C32 ORDERING INFORMATION

ROMless	TEMPERATURE RANGE °C AND PACKAGE	FREQ MHz	DRAWING NUMBER
P80C32SBP N	0 to +70, Plastic Dual In-line Package	16	SOT129-1
P80C32SBA A	0 to +70, Plastic Leaded Chip Carrier	16	SOT187-2
P80C32SBB B	0 to +70, Plastic Quad Flat Pack	16	SOT307-2
P80C32SFP N	–40 to +85, Plastic Dual In-line Package	16	SOT129-1
P80C32SFA A	–40 to +85, Plastic Leaded Chip Carrier	16	SOT187-2
P80C32SFB B	–40 to +85, Plastic Quad Flat Pack	16	SOT307-2
P80C32UBA A	0 to +70, Plastic Leaded Chip Carrier	33	SOT187-2
P80C32UBP N	0 to +70, Plastic Dual In-line Package	33	SOT129-1
P80C32UBB B	0 to +70, Plastic Quad Flat Pack	33	SOT307-2
P80C32UFA A	–40 to +85, Plastic Leaded Chip Carrier	33	SOT187-2
P80C32UFP N	–40 to +85, Plastic Dual In-line Package	33	SOT129-1
P80C32UFB B	–40 to +85, Plastic Quad Flat Pack	33	SOT307-2

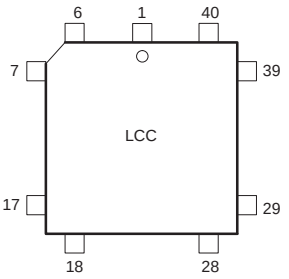
LOGIC SYMBOL



PIN CONFIGURATIONS



PLASTIC LEADED CHIP CARRIER PIN FUNCTIONS

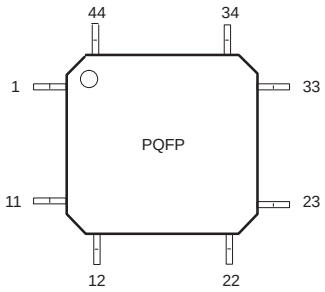


Pin	Function	Pin	Function	Pin	Function
1	NIC*	16	P3.4/T0	31	P2.7/A15
2	P1.0/T2	17	P3.5/T1	32	PSEN
3	P1.1/T2EX	18	P3.6/WR	33	ALE
4	P1.2	19	P3.7/RD	34	NIC*
5	P1.3	20	XTAL2	35	EA/VPP
6	P1.4	21	XTAL1	36	P0.7/AD7
7	P1.5	22	VSS	37	P0.6/AD6
8	P1.6	23	NIC*	38	P0.5/AD5
9	P1.7	24	P2.0/A8	39	P0.4/AD4
10	RST	25	P2.1/A9	40	P0.3/AD3
11	P3.0/RxD	26	P2.2/A10	41	P0.2/AD2
12	NIC*	27	P2.3/A11	42	P0.1/AD1
13	P3.1/TxD	28	P2.4/A12	43	P0.0/AD0
14	P3.2/INT0	29	P2.5/A13	44	VCC
15	P3.3/INT1	30	P2.6/A14		

* NO INTERNAL CONNECTION

SU01062

PLASTIC QUAD FLAT PACK PIN FUNCTIONS



Pin	Function	Pin	Function	Pin	Function
1	P1.5	16	VSS	31	P0.6/AD6
2	P1.6	17	NIC*	32	P0.5/AD5
3	P1.7	18	P2.0/A8	33	P0.4/AD4
4	RST	19	P2.1/A9	34	P0.3/AD3
5	P3.0/RxD	20	P2.2/A10	35	P0.2/AD2
6	NIC*	21	P2.3/A11	36	P0.1/AD1
7	P3.1/TxD	22	P2.4/A12	37	P0.0/AD0
8	P3.2/INT0	23	P2.5/A13	38	VCC
9	P3.3/INT1	24	P2.6/A14	39	NIC*
10	P3.4/T0	25	P2.7/A15	40	P1.0/T2
11	P3.5/T1	26	PSEN	41	P1.1/T2EX
12	P3.6/WR	27	ALE	42	P1.2
13	P3.7/RD	28	NIC*	43	P1.3
14	XTAL2	29	EA/VPP	44	P1.4
15	XTAL1	30	P0.7/AD7		

* NO INTERNAL CONNECTION

SU01064

Table 1. 8XC51/80C31 Special Function Registers

SYMBOL	DESCRIPTION	DIRECT ADDRESS	BIT ADDRESS, SYMBOL, OR ALTERNATIVE PORT FUNCTION MSB							LSB	RESET VALUE
ACC*	Accumulator	E0H	E7	E6	E5	E4	E3	E2	E1	E0	00H
AUXR#	Auxiliary	8EH	–	–	–	–	–	–	–	AO	xxxxxxx0B
AUXR1#	Auxiliary 1	A2H	–	–	–	–	WUPD[2]	0	–	DPS	xxx000x0B
B*	B register	F0H	F7	F6	F5	F4	F3	F2	F1	F0	00H
DPTR:	Data Pointer (2 bytes)										
DPH	Data Pointer High	83H									00H
DPL	Data Pointer Low	82H									00H
			AF	AE	AD	AC	AB	AA	A9	A8	
IE*	Interrupt Enable	A8H	EA	–	ET2	ES	ET1	EX1	ET0	EX0	0x000000B
			BF	BE	BD	BC	BB	BA	B9	B8	
IP*	Interrupt Priority	B8H	–	–	PT2	PS	PT1	PX1	PT0	PX0	xx000000B
			B7	B6	B5	B4	B3	B2	B1	B0	
IPH#	Interrupt Priority High	B7H	–	–	PT2H	PSH	PT1H	PX1H	PT0H	PX0H	xx000000B
			87	86	85	84	83	82	81	80	
P0*	Port 0	80H	AD7	AD6	AD5	AD4	AD3	AD2	AD1	AD0	FFH
			97	96	95	94	93	92	91	90	
P1*	Port 1	90H	–	–	–	–	–	–	T2EX	T2	FFH
			A7	A6	A5	A4	A3	A2	A1	A0	
P2*	Port 2	A0H	AD15	AD14	AD13	AD12	AD11	AD10	AD9	AD8	FFH
			B7	B6	B5	B4	B3	B2	B1	B0	
P3*	Port 3	B0H	$\overline{RD}$	$\overline{WR}$	T1	T0	$\overline{INT1}$	$\overline{INT0}$	TxD	RxD	FFH
PCON#[1]	Power Control	87H	SMOD1	SMOD0	–	POF	GF1	GF0	PD	IDL	00xx0000B
			D7	D6	D5	D4	D3	D2	D1	D0	
PSW*	Program Status Word	D0H	CY	AC	F0	RS1	RS0	OV	–	P	000000x0B
RACAP2H#	Timer 2 Capture High	CBH									00H
RACAP2L#	Timer 2 Capture Low	CAH									00H
SADDR#	Slave Address	A9H									00H
SADEN#	Slave Address Mask	B9H									00H
SBUF	Serial Data Buffer	99H									xxxxxxxxB
			9F	9E	9D	9C	9B	9A	99	98	
SCON*	Serial Control	98H	SM0/FE	SM1	SM2	REN	TB8	RB8	TI	RI	00H
SP	Stack Pointer	81H									07H
			8F	8E	8D	8C	8B	8A	89	88	
TCON*	Timer Control	88H	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0	00H
			CF	CE	CD	CC	CB	CA	C9	C8	
T2CON*	Timer 2 Control	C8H	TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/$\overline{T2}$	CP/$\overline{RL2}$	00H
T2MOD#	Timer 2 Mode Control	C9H	–	–	–	–	–	–	T2OE	DCEN	xxxxxx00B
TH0	Timer High 0	8CH									00H
TH1	Timer High 1	8DH									00H
TH2#	Timer High 2	CDH									00H
TL0	Timer Low 0	8AH									00H
TL1	Timer Low 1	8BH									00H
TL2#	Timer Low 2	CCH									00H
TMOD	Timer Mode	89H	GATE	C/$\overline{T}$	M1	M0	GATE	C/$\overline{T}$	M1	M0	00H

NOTE:
Unused register bits that are not defined should not be set by the user's program. If violated, the device could function incorrectly.
* SFRs are bit addressable.
\# SFRs are modified from or added to the 80C51 SFRs.
– Reserved bits.
1. Reset value depends on reset source.
2. Not available on 80C31.

(MSB)							(LSB)
TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/$\overline{T2}$	CP/$\overline{RL2}$

Symbol	Position	Name and Significance
TF2	T2CON.7	Timer 2 overflow flag set by a Timer 2 overflow and must be cleared by software. TF2 will not be set when either RCLK or TCLK = 1.
EXF2	T2CON.6	Timer 2 external flag set when either a capture or reload is caused by a negative transition on T2EX and EXEN2 = 1. When Timer 2 interrupt is enabled, EXF2 = 1 will cause the CPU to vector to the Timer 2 interrupt routine. EXF2 must be cleared by software. EXF2 does not cause an interrupt in up/down counter mode (DCEN = 1).
RCLK	T2CON.5	Receive clock flag. When set, causes the serial port to use Timer 2 overflow pulses for its receive clock in modes 1 and 3. RCLK = 0 causes Timer 1 overflow to be used for the receive clock.
TCLK	T2CON.4	Transmit clock flag. When set, causes the serial port to use Timer 2 overflow pulses for its transmit clock in modes 1 and 3. TCLK = 0 causes Timer 1 overflows to be used for the transmit clock.
EXEN2	T2CON.3	Timer 2 external enable flag. When set, allows a capture or reload to occur as a result of a negative transition on T2EX if Timer 2 is not being used to clock the serial port. EXEN2 = 0 causes Timer 2 to ignore events at T2EX.
TR2	T2CON.2	Start/stop control for Timer 2. A logic 1 starts the timer.
C/$\overline{T2}$	T2CON.1	Timer or counter select. (Timer 2) 0 = Internal timer (OSC/12) 1 = External event counter (falling edge triggered).
CP/$\overline{RL2}$	T2CON.0	Capture/Reload flag. When set, captures will occur on negative transitions at T2EX if EXEN2 = 1. When cleared, auto-reloads will occur either with Timer 2 overflows or negative transitions at T2EX when EXEN2 = 1. When either RCLK = 1 or TCLK = 1, this bit is ignored and the timer is forced to auto-reload on Timer 2 overflow.

SU00728

Figure 1. Timer/Counter 2 (T2CON) Control Register

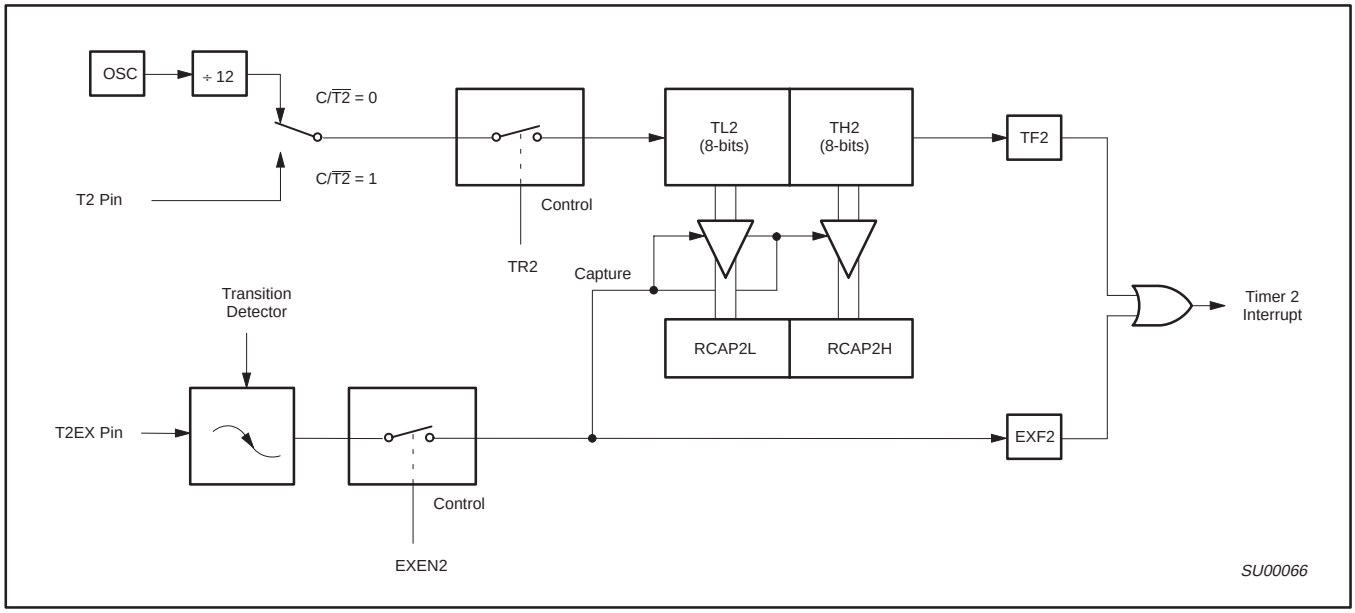


Figure 2. Timer 2 in Capture Mode

T2MOD Address = 0C9H Reset Value = XXXX XX00B

Not Bit Addressable

—	—	—	—	—	—	T2OE	DCEN
Bit 7	6	5	4	3	2	1	0

Symbol	Function
—	Not implemented, reserved for future use.*
T2OE	Timer 2 Output Enable bit.
DCEN	Down Count Enable bit. When set, this allows Timer 2 to be configured as an up/down counter.

* User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.

SU00729

Figure 3. Timer 2 Mode (T2MOD) Control Register

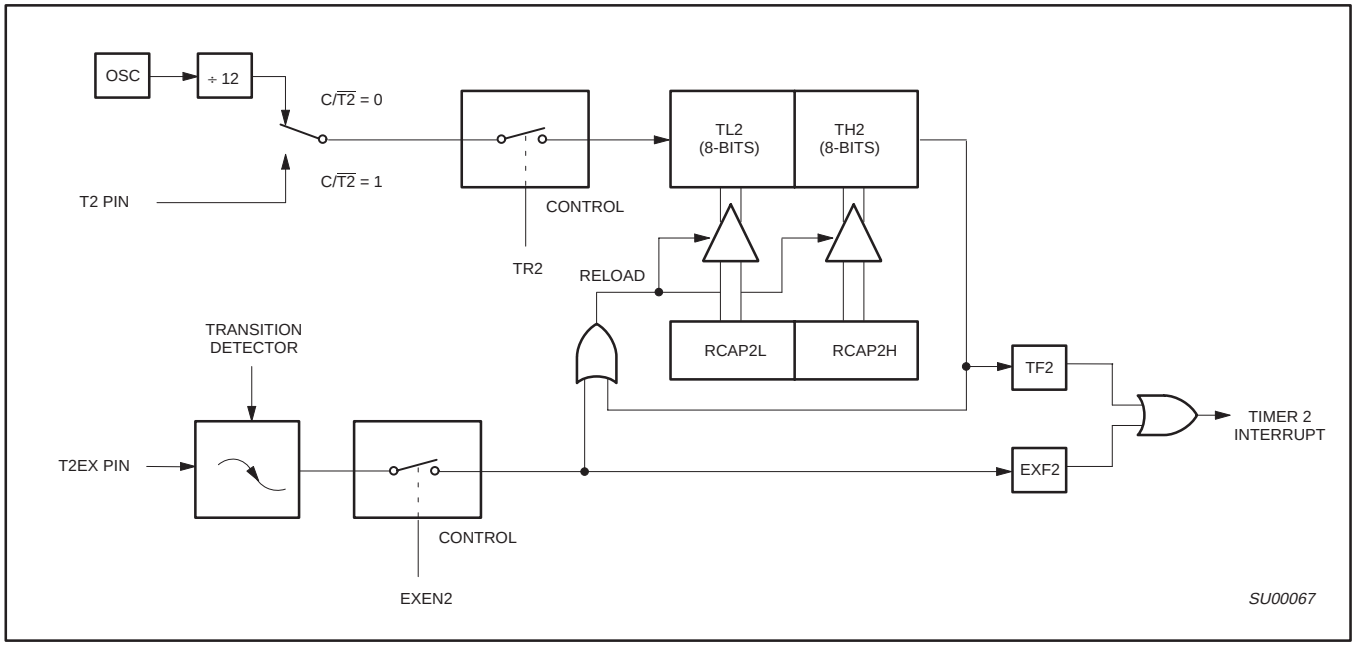


Figure 4. Timer 2 in Auto-Reload Mode (DCEN = 0)

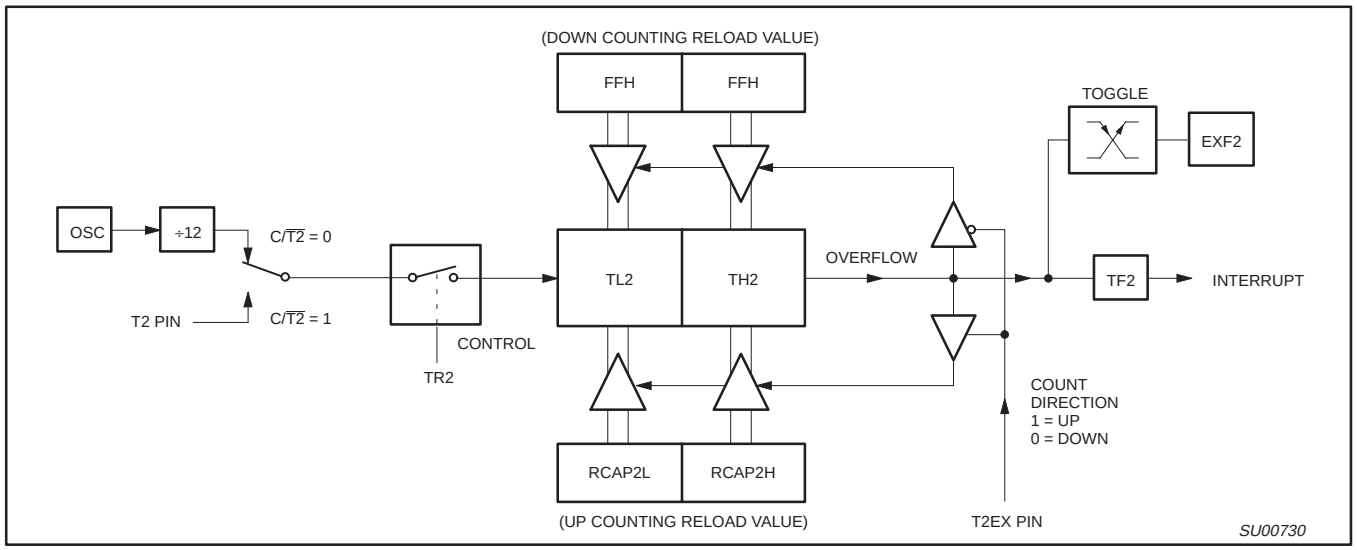


Figure 5. Timer 2 Auto Reload Mode (DCEN = 1)

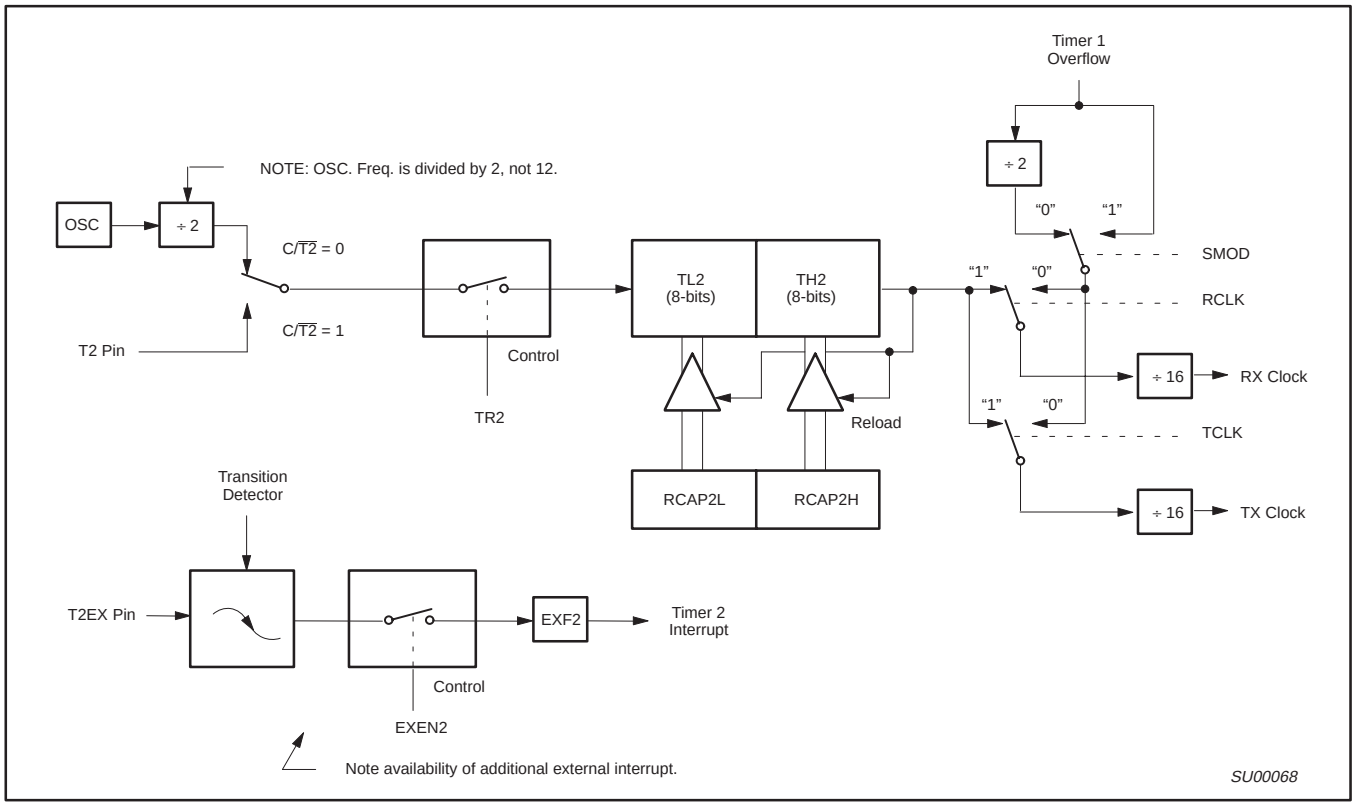


Figure 6. Timer 2 in Baud Rate Generator Mode

and 1 and exclude Slave 2 use address 1110 0100, since it is necessary to make bit 2 = 1 to exclude slave 2.

The Broadcast Address for each slave is created by taking the logical OR of SADDR and SADEN. Zeros in this result are trended as don't-cares. In most cases, interpreting the don't-cares as ones, the broadcast address will be FF hexadecimal.

Upon reset SADDR (SFR address 0A9H) and SADEN (SFR address 0B9H) are leaded with 0s. This produces a given address of all "don't cares" as well as a Broadcast address of all "don't cares". This effectively disables the Automatic Addressing mode and allows the microcontroller to use standard 80C51 type UART drivers which do not make use of this feature.

SCON Address = 98H — Reset Value = 0000 0000B

Bit Addressable

	SM0/FE	SM1	SM2	REN	TB8	RB8	TI	RI
Bit:	7	6	5	4	3	2	1	0
	(SMOD0 = 0/1)*							

Symbol	Function
FE	Framing Error bit. This bit is set by the receiver when an invalid stop bit is detected. The FE bit is not cleared by valid frames but should be cleared by software. The SMOD0 bit must be set to enable access to the FE bit.
SM0	Serial Port Mode Bit 0, (SMOD0 must = 0 to access bit SM0)
SM1	Serial Port Mode Bit 1

SM0	SM1	Mode	Description	Baud Rate**
0	0	0	shift register	$f_{OSC}/12$
0	1	1	8-bit UART	variable
1	0	2	9-bit UART	$f_{OSC}/64$ or $f_{OSC}/32$
1	1	3	9-bit UART	variable

SM2	Enables the Automatic Address Recognition feature in Modes 2 or 3. If SM2 = 1 then RI will not be set unless the received 9th data bit (RB8) is 1, indicating an address, and the received byte is a Given or Broadcast Address. In Mode 1, if SM2 = 1 then RI will not be activated unless a valid stop bit was received, and the received byte is a Given or Broadcast Address. In Mode 0, SM2 should be 0.
REN	Enables serial reception. Set by software to enable reception. Clear by software to disable reception.
TB8	The 9th data bit that will be transmitted in Modes 2 and 3. Set or clear by software as desired.
RB8	In modes 2 and 3, the 9th data bit that was received. In Mode 1, if SM2 = 0, RB8 is the stop bit that was received. In Mode 0, RB8 is not used.
TI	Transmit interrupt flag. Set by hardware at the end of the 8th bit time in Mode 0, or at the beginning of the stop bit in the other modes, in any serial transmission. Must be cleared by software.
RI	Receive interrupt flag. Set by hardware at the end of the 8th bit time in Mode 0, or halfway through the stop bit time in the other modes, in any serial reception (except see SM2). Must be cleared by software.

NOTE:
*SMOD0 is located at PCON6.
**f_{OSC} = oscillator frequency

SU00043

Figure 7. SCON: Serial Port Control Register

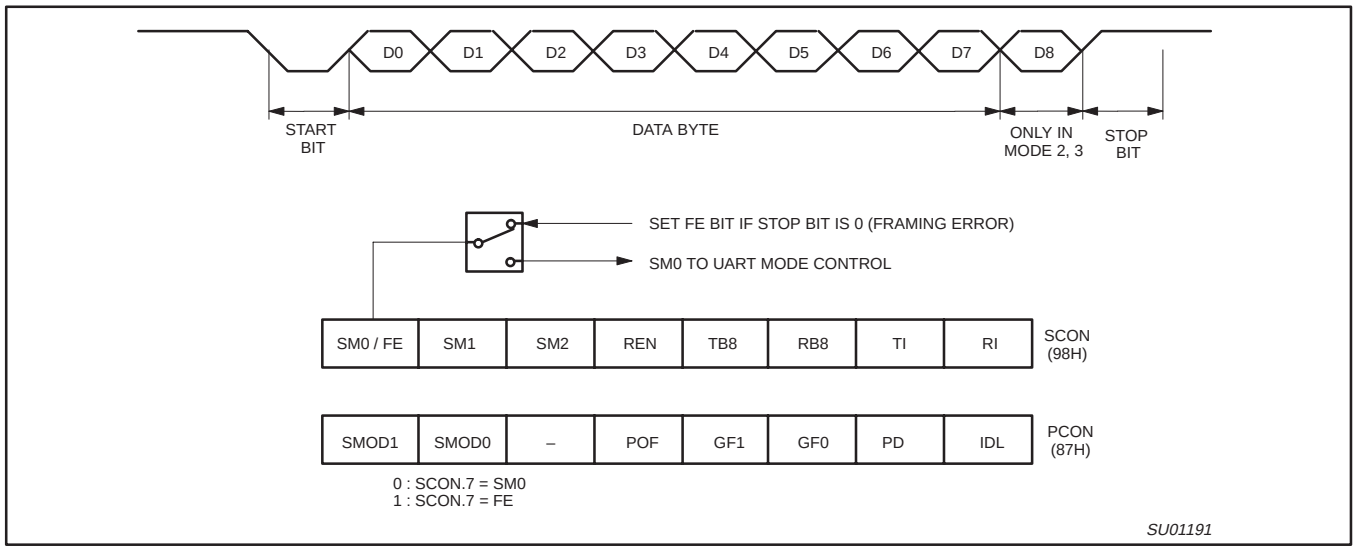


Figure 8. UART Framing Error Detection

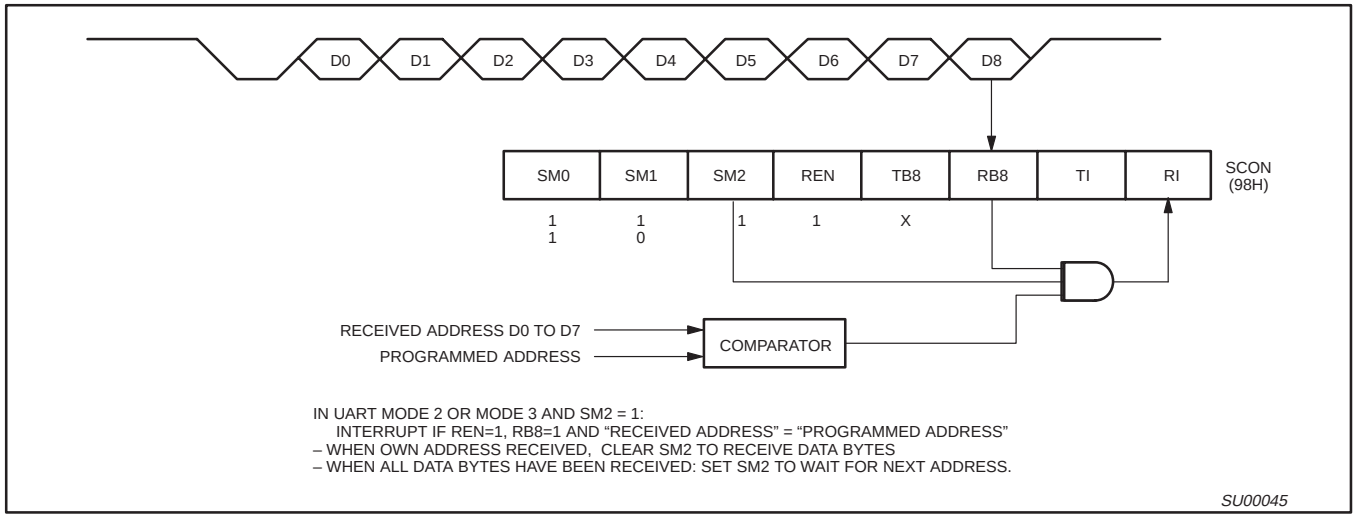


Figure 9. UART Multiprocessor Communication, Automatic Address Recognition

Interrupt Priority Structure

The 80C31 and 80C32 have a 6-source four-level interrupt structure. They are the IE, IP and IPH. (See Figures 10, 11, and 12.) The IPH (Interrupt Priority High) register that makes the four-level interrupt structure possible. The IPH is located at SFR address B7H. The structure of the IPH register and a description of its bits is shown in Figure 12.

The function of the IPH SFR is simple and when combined with the IP SFR determines the priority of each interrupt. The priority of each interrupt is determined as shown in the following table:

PRIORITY BITS		INTERRUPT PRIORITY LEVEL
IPH.x	IP.x	
0	0	Level 0 (lowest priority)
0	1	Level 1
1	0	Level 2
1	1	Level 3 (highest priority)

An interrupt will be serviced as long as an interrupt of equal or higher priority is not already being serviced. If an interrupt of equal or higher level priority is being serviced, the new interrupt will wait until it is finished before being serviced. If a lower priority level interrupt is being serviced, it will be stopped and the new interrupt serviced. When the new interrupt is finished, the lower priority level interrupt that was stopped will be completed.

Table 7. Interrupt Table

SOURCE	POLLING PRIORITY	REQUEST BITS	HARDWARE CLEAR?	VECTOR ADDRESS
X0	1	IE0	N (L)[1] Y (T)[2]	03H
T0	2	TP0	Y	0BH
X1	3	IE1	N (L) Y (T)	13H
T1	4	TF1	Y	1BH
SP	5	RI, TI	N	23H
T2	6	TF2, EXF2	N	2BH

NOTES:
1. L = Level activated
2. T = Transition activated

	7	6	5	4	3	2	1	0
IE (0A8H)	EA	—	ET2	ES	ET1	EX1	ET0	EX0

Enable Bit = 1 enables the interrupt.
Enable Bit = 0 disables it.

BIT	SYMBOL	FUNCTION
IE.7	EA	Global disable bit. If EA = 0, all interrupts are disabled. If EA = 1, each interrupt can be individually enabled or disabled by setting or clearing its enable bit.
IE.6	—	Not implemented. Reserved for future use.
IE.5	ET2	Timer 2 interrupt enable bit.
IE.4	ES	Serial Port interrupt enable bit.
IE.3	ET1	Timer 1 interrupt enable bit.
IE.2	EX1	External interrupt 1 enable bit.
IE.1	ET0	Timer 0 interrupt enable bit.
IE.0	EX0	External interrupt 0 enable bit.

SU00571

Figure 10. IE Registers

Reduced EMI Mode

The AO bit (AUXR.0) in the AUXR register when set disables the ALE output.

Reduced EMI Mode

AUXR (8EH)

7	6	5	4	3	2	1	0
–	–	–	–	–	–	–	AO

AUXR.0 AO Turns off ALE output.

Dual DPTR

The dual DPTR structure (see Figure 13) enables a way to specify the address of an external data memory location. There are two 16-bit DPTR registers that address the external memory, and a single bit called DPS = AUXR1/bit0 that allows the program code to switch between them.

- New Register Name: AUXR1#
- SFR Address: A2H
- Reset Value: xxx000x0B

AUXR1 (A2H)

7	6	5	4	3	2	1	0
–	–	–	–	WUPD	0	–	DPS

Where:
DPS = AUXR1/bit0 = Switches between DPTR0 and DPTR1.

Select Reg	DPS
DPTR0	0
DPTR1	1

The DPS bit status should be saved by software when switching between DPTR0 and DPTR1.

Note that bit 2 is not writable and is always read as a zero. This allows the DPS bit to be quickly toggled simply by executing an INC DPTR instruction without affecting the WOPD or LPEP bits.

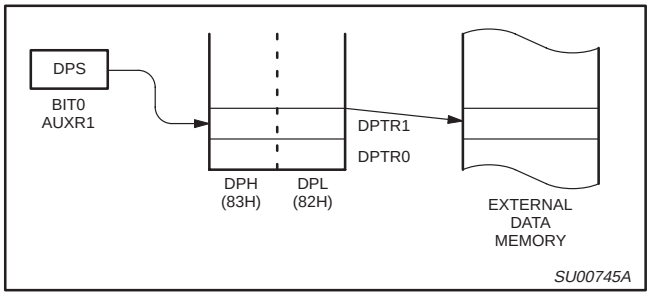


Figure 13.

DPTR Instructions

The instructions that refer to DPTR refer to the data pointer that is currently selected using the AUXR1/bit 0 register. The six instructions that use the DPTR are as follows:

INC DPTR	Increments the data pointer by 1
MOV DPTR, #data16	Loads the DPTR with a 16-bit constant
MOV A, @ A+DPTR	Move code byte relative to DPTR to ACC
MOVX A, @ DPTR	Move external RAM (16-bit address) to ACC
MOVX @ DPTR , A	Move ACC to external RAM (16-bit address)
JMP @ A + DPTR	Jump indirect relative to DPTR

The data pointer can be accessed on a byte-by-byte basis by specifying the low or high byte in an instruction which accesses the SFRs. See application note AN458 for more details.

DC ELECTRICAL CHARACTERISTICS

T_{amb} = 0°C to +70°C or –40°C to +85°C, V_{CC} = 2.7 V to 5.5 V, V_{SS} = 0 V (16 MHz devices)

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP[1]	MAX	
V_{IL}	Input low voltage	4.0 V < V_{CC} < 5.5 V	–0.5		0.2 V_{CC}–0.1	V
		2.7 V<V_{CC}< 4.0 V	–0.5		0.7	V
V_{IH}	Input high voltage (ports 0, 1, 2, 3, $\overline{EA}$)		0.2 V_{CC}+0.9		V_{CC}+0.5	V
V_{IH1}	Input high voltage, XTAL1, RST		0.7 V_{CC}		V_{CC}+0.5	V
V_{OL}	Output low voltage, ports 1, 2, [8]	V_{CC} = 2.7 V I_{OL} = 1.6 mA[2]			0.4	V
V_{OL1}	Output low voltage, port 0, ALE, $\overline{PSEN}$[8, 7]	V_{CC} = 2.7 V I_{OL} = 3.2 mA[2]			0.4	V
V_{OH}	Output high voltage, ports 1, 2, 3 [3]	V_{CC} = 2.7 V I_{OH} = –20 µA	V_{CC} – 0.7			V
		V_{CC} = 4.5 V I_{OH} = –30 µA	V_{CC} – 0.7			V
V_{OH1}	Output high voltage (port 0 in external bus mode), ALE[9], $\overline{PSEN}$[3]	V_{CC} = 2.7 V I_{OH} = –3.2 mA	V_{CC} – 0.7			V
I_{IL}	Logical 0 input current, ports 1, 2, 3	V_{IN} = 0.4 V	–1		–50	µA
I_{TL}	Logical 1-to-0 transition current, ports 1, 2, 3[6]	V_{IN} = 2.0 V See note 4			–650	µA
I_{LI}	Input leakage current, port 0	0.45 < V_{IN} < V_{CC} – 0.3			±10	µA
I_{CC}	Power supply current (see Figure 21): Active mode @ 16 MHz Idle mode @ 16 MHz Power-down mode or clock stopped (see Figure 25 for conditions)	See note 5 T_{amb} = 0°C to 70°C T_{amb} = –40°C to +85°C		 3	 50 75	 µA µA µA µA
R_{RST}	Internal reset pull-down resistor		40		225	kΩ
C_{IO}	Pin capacitance[10] (except $\overline{EA}$)				15	pF

NOTES:

1. Typical ratings are not guaranteed. The values listed are at room temperature, 5 V.
2. Capacitive loading on ports 0 and 2 may cause spurious noise to be superimposed on the V_{OL}s of ALE and ports 1 and 3. The noise is due to external bus capacitance discharging into the port 0 and port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100 pF), the noise pulse on the ALE pin may exceed 0.8 V. In such cases, it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input. I_{OL} can exceed these conditions provided that no single output sinks more than 5 mA and no more than two outputs exceed the test conditions.
3. Capacitive loading on ports 0 and 2 may cause the V_{OH} on ALE and $\overline{PSEN}$ to momentarily fall below the V_{CC}–0.7 specification when the address bits are stabilizing.
4. Pins of ports 1, 2 and 3 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its maximum value when V_{IN} is approximately 2 V.
5. See Figures 22 through 25 for I_{CC} test conditions.
   Active mode: I_{CC} = 0.9 × FREQ. + 1.1 mA
   Idle mode: I_{CC} = 0.18 × FREQ. +1.01 mA; See Figure 21.
6. This value applies to T_{amb} = 0°C to +70°C. For T_{amb} = –40°C to +85°C, I_{TL} = –750 µA.
7. Load capacitance for port 0, ALE, and $\overline{PSEN}$ = 100 pF, load capacitance for all other outputs = 80 pF.
8. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
   Maximum I_{OL} per port pin: 15 mA (*NOTE: This is 85°C specification.)
   Maximum I_{OL} per 8-bit port: 26 mA
   Maximum total I_{OL} for all outputs: 71 mA
   If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
9. ALE is tested to V_{OH1}, except when ALE is off then V_{OH} is the voltage specification.
10. Pin capacitance is characterized but not tested. Pin capacitance is less than 25 pF.

AC ELECTRICAL CHARACTERISTICS

T_{amb} = 0°C to +70°C or –40°C to +85°C, V_{CC} = +2.7 V to +5.5 V, V_{SS} = 0 V[1, 2, 3]

SYMBOL	FIGURE	PARAMETER	16 MHz CLOCK		VARIABLE CLOCK		UNIT
			MIN	MAX	MIN	MAX	
$1/t_{CLCL}$	14	Oscillator frequency[5] Speed versions :S			3.5	16	MHz
t_{LHLL}	14	ALE pulse width	85		$2t_{CLCL}$–40		ns
t_{AVLL}	14	Address valid to ALE low	22		t_{CLCL}–40		ns
t_{LLAX}	14	Address hold after ALE low	32		t_{CLCL}–30		ns
t_{LLIV}	14	ALE low to valid instruction in		150		$4t_{CLCL}$–100	ns
t_{LLPL}	14	ALE low to $\overline{PSEN}$ low	32		t_{CLCL}–30		ns
t_{PLPH}	14	$\overline{PSEN}$ pulse width	142		$3t_{CLCL}$–45		ns
t_{PLIV}	14	$\overline{PSEN}$ low to valid instruction in		82		$3t_{CLCL}$–105	ns
t_{PXIX}	14	Input instruction hold after $\overline{PSEN}$	0		0		ns
t_{PXIZ}	14	Input instruction float after $\overline{PSEN}$		37		t_{CLCL}–25	ns
t_{AVIV} [4]	14	Address to valid instruction in		207		$5t_{CLCL}$–105	ns
t_{PLAZ}	14	$\overline{PSEN}$ low to address float		10		10	ns
Data Memory							
t_{RLRH}	15, 16	$\overline{RD}$ pulse width	275		$6t_{CLCL}$–100		ns
t_{WLWH}	15, 16	$\overline{WR}$ pulse width	275		$6t_{CLCL}$–100		ns
t_{RLDV}	15, 16	$\overline{RD}$ low to valid data in		147		$5t_{CLCL}$–165	ns
t_{RHDX}	15, 16	Data hold after $\overline{RD}$	0		0		ns
t_{RHDZ}	15, 16	Data float after $\overline{RD}$		65		$2t_{CLCL}$–60	ns
t_{LLDV}	15, 16	ALE low to valid data in		350		$8t_{CLCL}$–150	ns
t_{AVDV}	15, 16	Address to valid data in		397		$9t_{CLCL}$–165	ns
t_{LLWL}	15, 16	ALE low to $\overline{RD}$ or $\overline{WR}$ low	137	239	$3t_{CLCL}$–50	$3t_{CLCL}$+50	ns
t_{AVWL}	15, 16	Address valid to $\overline{WR}$ low or $\overline{RD}$ low	122		$4t_{CLCL}$–130		ns
t_{QVWX}	15, 16	Data valid to $\overline{WR}$ transition	13		t_{CLCL}–50		ns
t_{WHQX}	15, 16	Data hold after $\overline{WR}$	13		t_{CLCL}–50		ns
t_{QVWH}	16	Data valid to $\overline{WR}$ high	287		$7t_{CLCL}$–150		ns
t_{RLAZ}	15, 16	$\overline{RD}$ low to address float		0		0	ns
t_{WHLH}	15, 16	$\overline{RD}$ or $\overline{WR}$ high to ALE high	23	103	t_{CLCL}–40	t_{CLCL}+40	ns
External Clock							
t_{CHCX}	18	High time	20		20	t_{CLCL}–t_{CLCX}	ns
t_{CLCX}	18	Low time	20		20	t_{CLCL}–t_{CHCX}	ns
t_{CLCH}	18	Rise time		20		20	ns
t_{CHCL}	18	Fall time		20		20	ns
Shift Register							
t_{XLXL}	17	Serial port clock cycle time	750		$12t_{CLCL}$		ns
t_{QVXH}	17	Output data setup to clock rising edge	492		$10t_{CLCL}$–133		ns
t_{XHQX}	17	Output data hold after clock rising edge	8		$2t_{CLCL}$–117		ns
t_{XHDX}	17	Input data hold after clock rising edge	0		0		ns
t_{XHDV}	17	Clock rising edge to input data valid		492		$10t_{CLCL}$–133	ns

NOTES:
1. Parameters are valid over operating temperature range unless otherwise specified.
2. Load capacitance for port 0, ALE, and $\overline{PSEN}$ = 100 pF, load capacitance for all other outputs = 80 pF.
3. Interfacing the 80C31 and 80C32 to devices with float times up to 45ns is permitted. This limited bus contention will not cause damage to Port 0 drivers.
4. See application note AN457 for external memory interface.
5. Parts are guaranteed to operate down to 0 Hz. When an external clock source is used, the RST pin should be held high for a minimum of 20 μs for power-on or wakeup from power down.

AC ELECTRICAL CHARACTERISTICS

T_{amb} = 0°C to +70°C or –40°C to +85°C, V_{CC} = 5 V ±10%, V_{SS} = 0 V[1, 2, 3]

SYMBOL	FIGURE	PARAMETER	VARIABLE CLOCK[4] 16 MHz to f_{max}		33 MHz CLOCK		UNIT
			MIN	MAX	MIN	MAX	
t_{LHLL}	14	ALE pulse width	$2t_{CLCL}$–40		21		ns
t_{AVLL}	14	Address valid to ALE low	t_{CLCL}–25		5		ns
t_{LLAX}	14	Address hold after ALE low	t_{CLCL}–25				ns
t_{LLIV}	14	ALE low to valid instruction in		$4t_{CLCL}$–65		55	ns
t_{LLPL}	14	ALE low to $\overline{PSEN}$ low	t_{CLCL}–25		5		ns
t_{PLPH}	14	$\overline{PSEN}$ pulse width	$3t_{CLCL}$–45		45		ns
t_{PLIV}	14	$\overline{PSEN}$ low to valid instruction in		$3t_{CLCL}$–60		30	ns
t_{PXIX}	14	Input instruction hold after $\overline{PSEN}$	0		0		ns
t_{PXIZ}	14	Input instruction float after $\overline{PSEN}$		t_{CLCL}–25		5	ns
t_{AVIV}	14	Address to valid instruction in		$5t_{CLCL}$–80		70	ns
t_{PLAZ}	14	$\overline{PSEN}$ low to address float		10		10	ns
Data Memory							
t_{RLRH}	15, 16	$\overline{RD}$ pulse width	$6t_{CLCL}$–100		82		ns
t_{WLWH}	15, 16	$\overline{WR}$ pulse width	$6t_{CLCL}$–100		82		ns
t_{RLDV}	15, 16	$\overline{RD}$ low to valid data in		$5t_{CLCL}$–90		60	ns
t_{RHDX}	15, 16	Data hold after $\overline{RD}$	0		0		ns
t_{RHDZ}	15, 16	Data float after $\overline{RD}$		$2t_{CLCL}$–28		32	ns
t_{LLDV}	15, 16	ALE low to valid data in		$8t_{CLCL}$–150		90	ns
t_{AVDV}	15, 16	Address to valid data in		$9t_{CLCL}$–165		105	ns
t_{LLWL}	15, 16	ALE low to $\overline{RD}$ or $\overline{WR}$ low	$3t_{CLCL}$–50	$3t_{CLCL}$+50	40	140	ns
t_{AVWL}	15, 16	Address valid to $\overline{WR}$ low or $\overline{RD}$ low	$4t_{CLCL}$–75		45		ns
t_{QVWX}	15, 16	Data valid to $\overline{WR}$ transition	t_{CLCL}–30		0		ns
t_{WHQX}	15, 16	Data hold after $\overline{WR}$	t_{CLCL}–25		5		ns
t_{QVWH}	16	Data valid to $\overline{WR}$ high	$7t_{CLCL}$–130		80		ns
t_{RLAZ}	15, 16	$\overline{RD}$ low to address float		0		0	ns
t_{WHLH}	15, 16	$\overline{RD}$ or $\overline{WR}$ high to ALE high	t_{CLCL}–25	t_{CLCL}+25	5	55	ns
External Clock							
t_{CHCX}	18	High time	$0.38t_{CLCL}$	t_{CLCL}–t_{CLCX}			ns
t_{CLCX}	18	Low time	$0.38t_{CLCL}$	t_{CLCL}–t_{CHCX}			ns
t_{CLCH}	18	Rise time		5			ns
t_{CHCL}	18	Fall time		5			ns
Shift Register							
t_{XLXL}	17	Serial port clock cycle time	$12t_{CLCL}$		360		ns
t_{QVXH}	17	Output data setup to clock rising edge	$10t_{CLCL}$–133		167		ns
t_{XHQX}	17	Output data hold after clock rising edge	$2t_{CLCL}$–80				ns
t_{XHDX}	17	Input data hold after clock rising edge	0		0		ns
t_{XHDV}	17	Clock rising edge to input data valid		$10t_{CLCL}$–133		167	ns

NOTES:
1. Parameters are valid over operating temperature range unless otherwise specified.
2. Load capacitance for port 0, ALE, and $\overline{PSEN}$ = 100 pF, load capacitance for all other outputs = 80 pF.
3. Interfacing the 80C31 and 80C32 to devices with float times up to 45ns is permitted. This limited bus contention will not cause damage to Port 0 drivers.
4. Variable clock is specified for oscillator frequencies greater than 16 MHz to 33 MHz. For frequencies equal or less than 16 MHz, see 16 MHz "AC Electrical Characteristics", page 23.
5. Parts are guaranteed to operate down to 0 Hz. When an external clock source is used, the RST pin should be held high for a minimum of 20 μs for power-on or wakeup from power down.

EXPLANATION OF THE AC SYMBOLS

Each timing symbol has five characters. The first character is always 't' (= time). The other characters, depending on their positions, indicate the name of a signal or the logical status of that signal. The designations are:

A – Address
C – Clock
D – Input data
H – Logic level high
I – Instruction (program memory contents)
L – Logic level low, or ALE
P – $\overline{\text{PSEN}}$
Q – Output data
R – $\overline{\text{RD}}$ signal
t – Time
V – Valid
W – $\overline{\text{WR}}$ signal
X – No longer a valid logic level
Z – Float

Examples: t_{AVLL} = Time for address valid to ALE low.
t_{LLPL} =Time for ALE low to $\overline{\text{PSEN}}$ low.

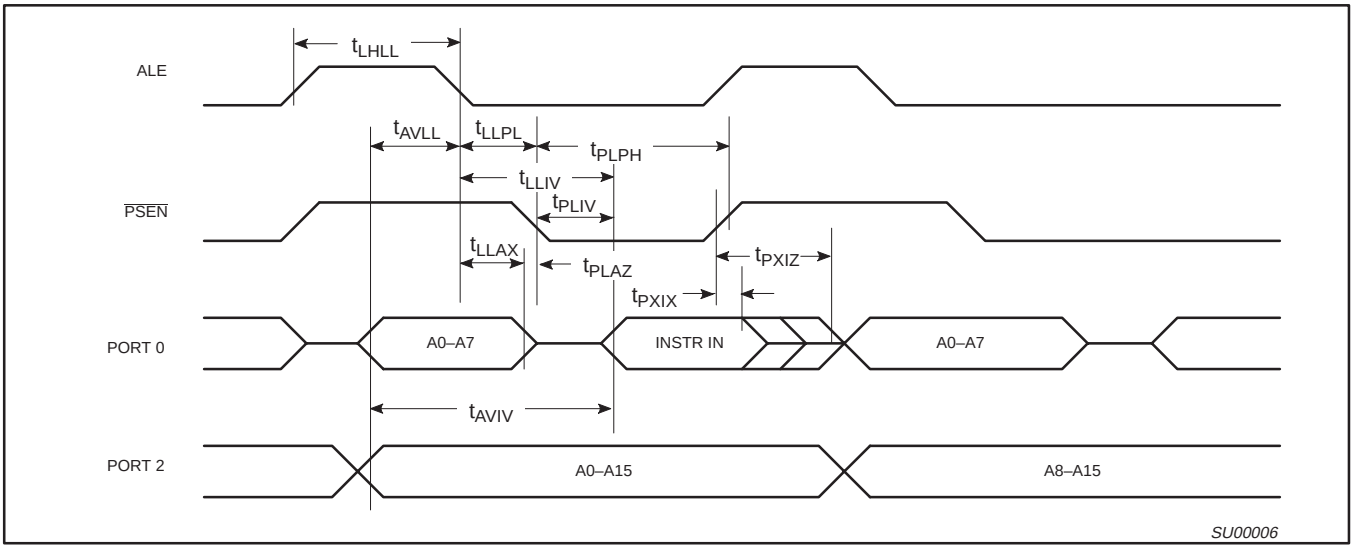


Figure 14. External Program Memory Read Cycle

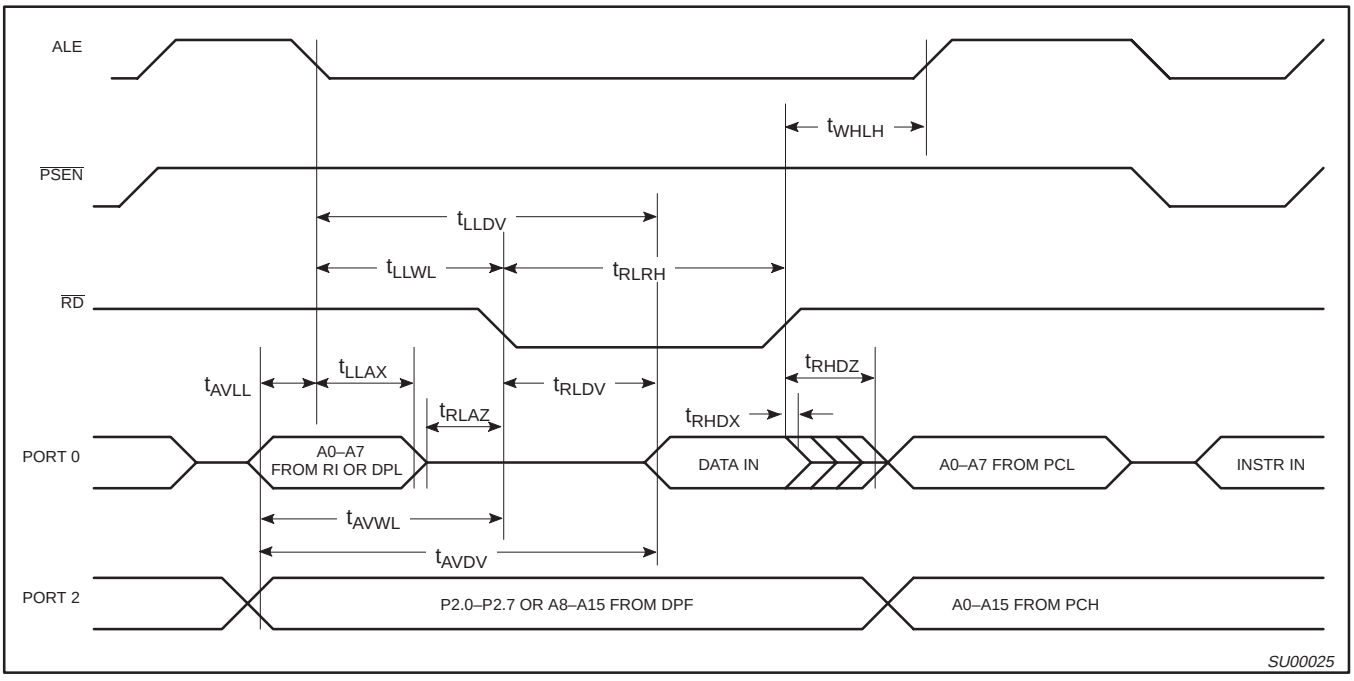


Figure 15. External Data Memory Read Cycle

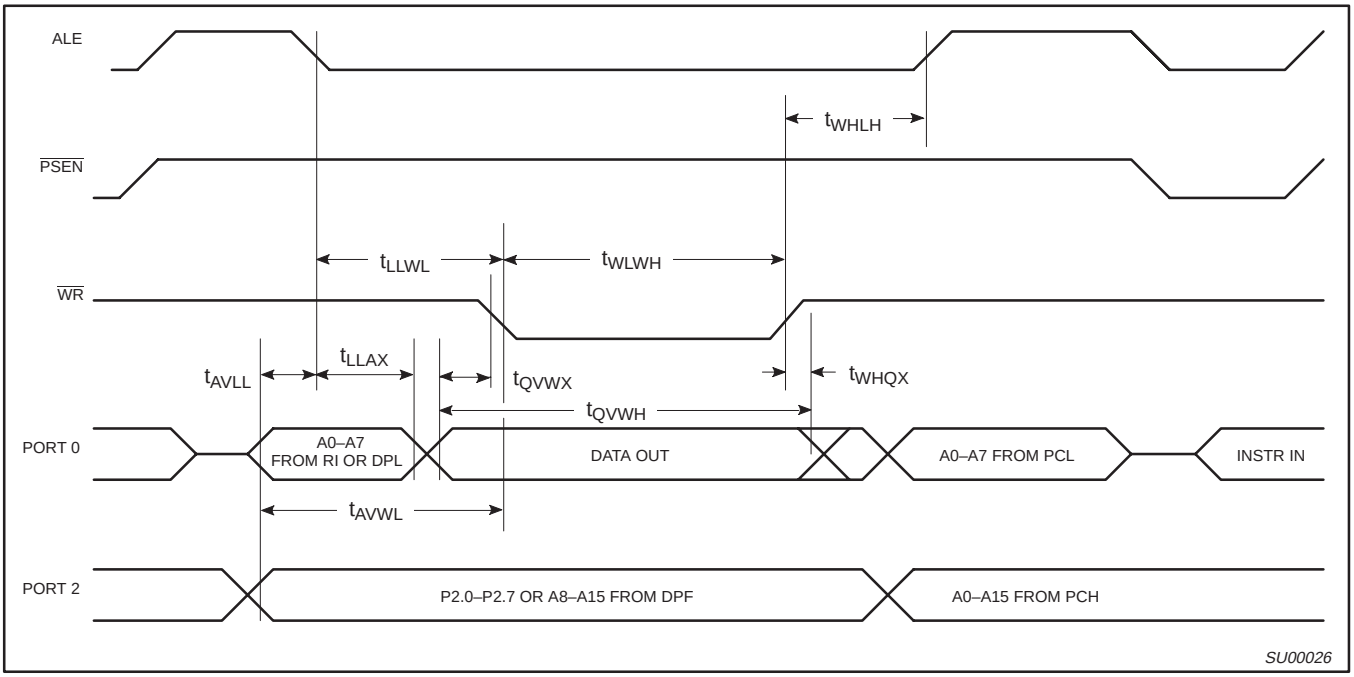


Figure 16. External Data Memory Write Cycle

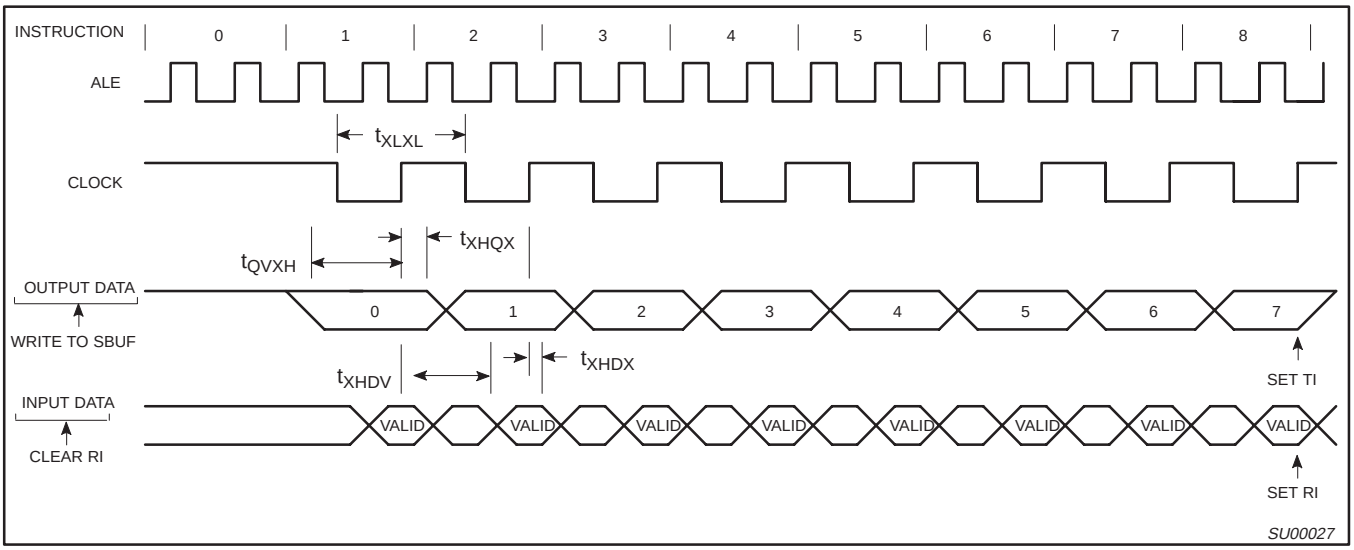


Figure 17. Shift Register Mode Timing

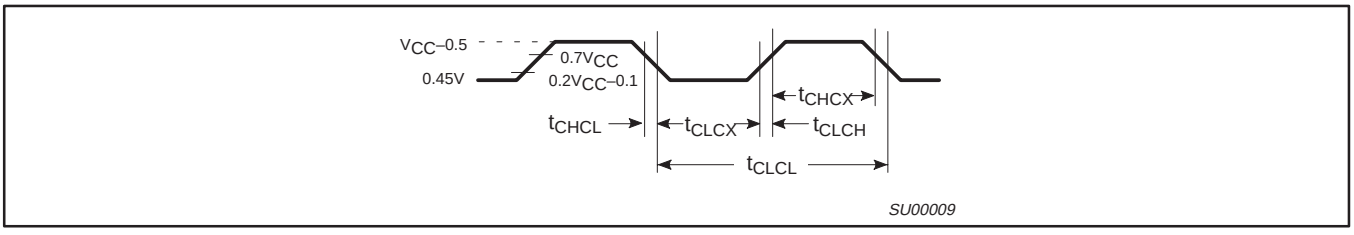
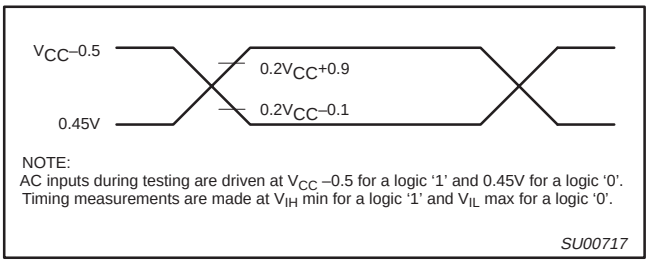


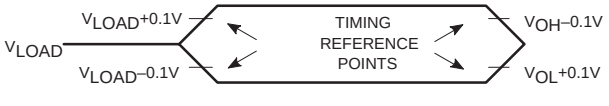
Figure 18. External Clock Drive



NOTE:
AC inputs during testing are driven at V_{CC} –0.5 for a logic '1' and 0.45V for a logic '0'. Timing measurements are made at V_{IH} min for a logic '1' and V_{IL} max for a logic '0'.

SU00717

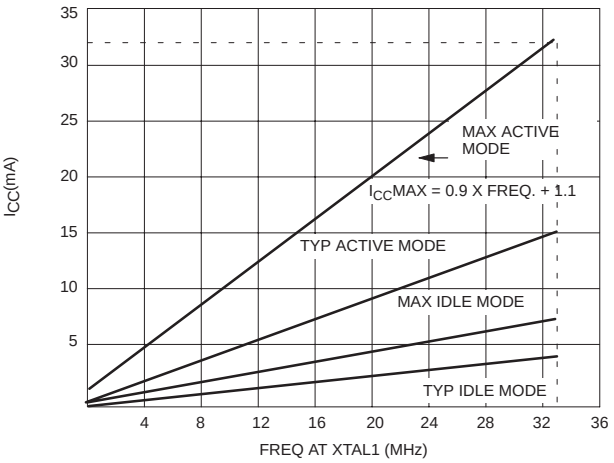
Figure 19. AC Testing Input/Output



NOTE:
For timing purposes, a port is no longer floating when a 100mV change from load voltage occurs, and begins to float when a 100mV change from the loaded V_{OH}/V_{OL} level occurs. $I_{OH}/I_{OL} \geq \pm 20$mA.

SU00718

Figure 20. Float Waveform



SU01413

Figure 21. I_{CC} vs. FREQ
Valid only within frequency specifications of the device under test

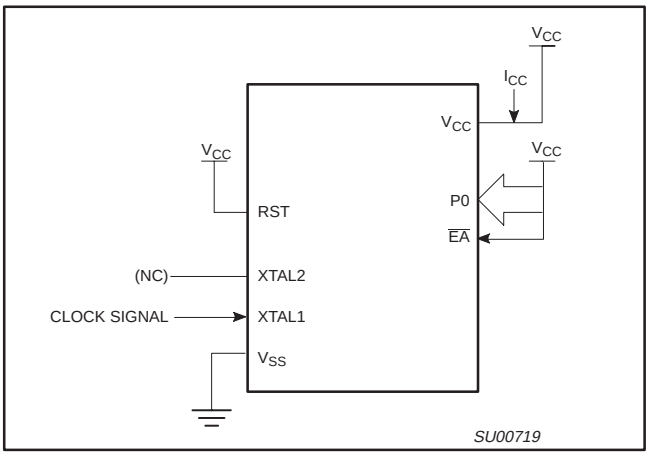


Figure 22. I_{CC} Test Condition, Active Mode
All other pins are disconnected

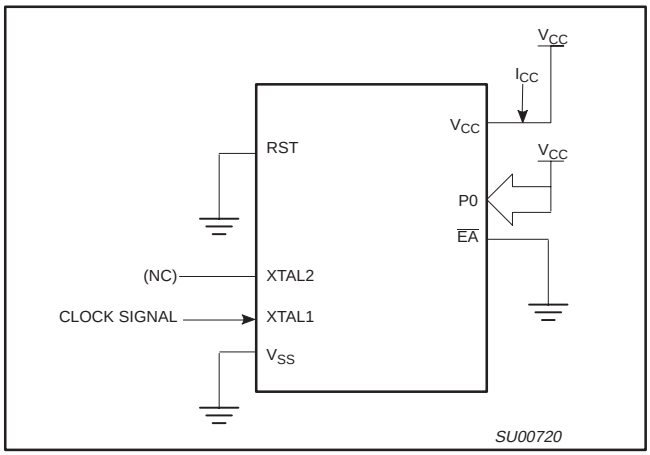


Figure 23. I_{CC} Test Condition, Idle Mode
All other pins are disconnected

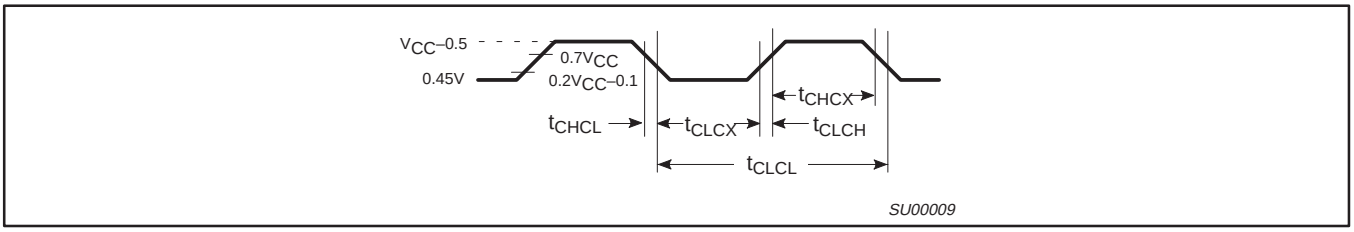


Figure 24. Clock Signal Waveform for I_{CC} Tests in Active and Idle Modes
$t_{CLCH} = t_{CHCL} = 5ns$

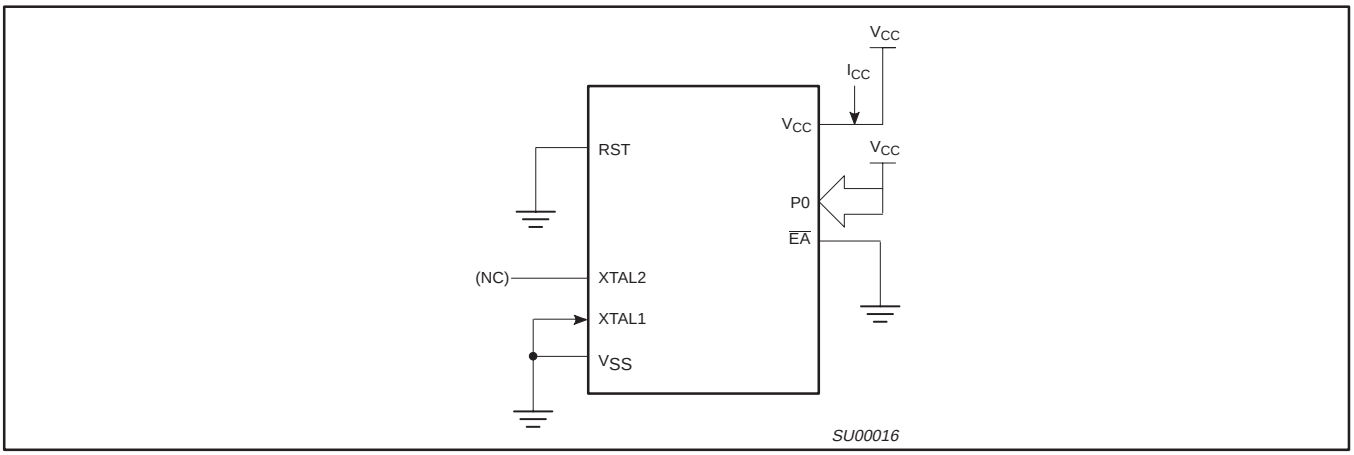
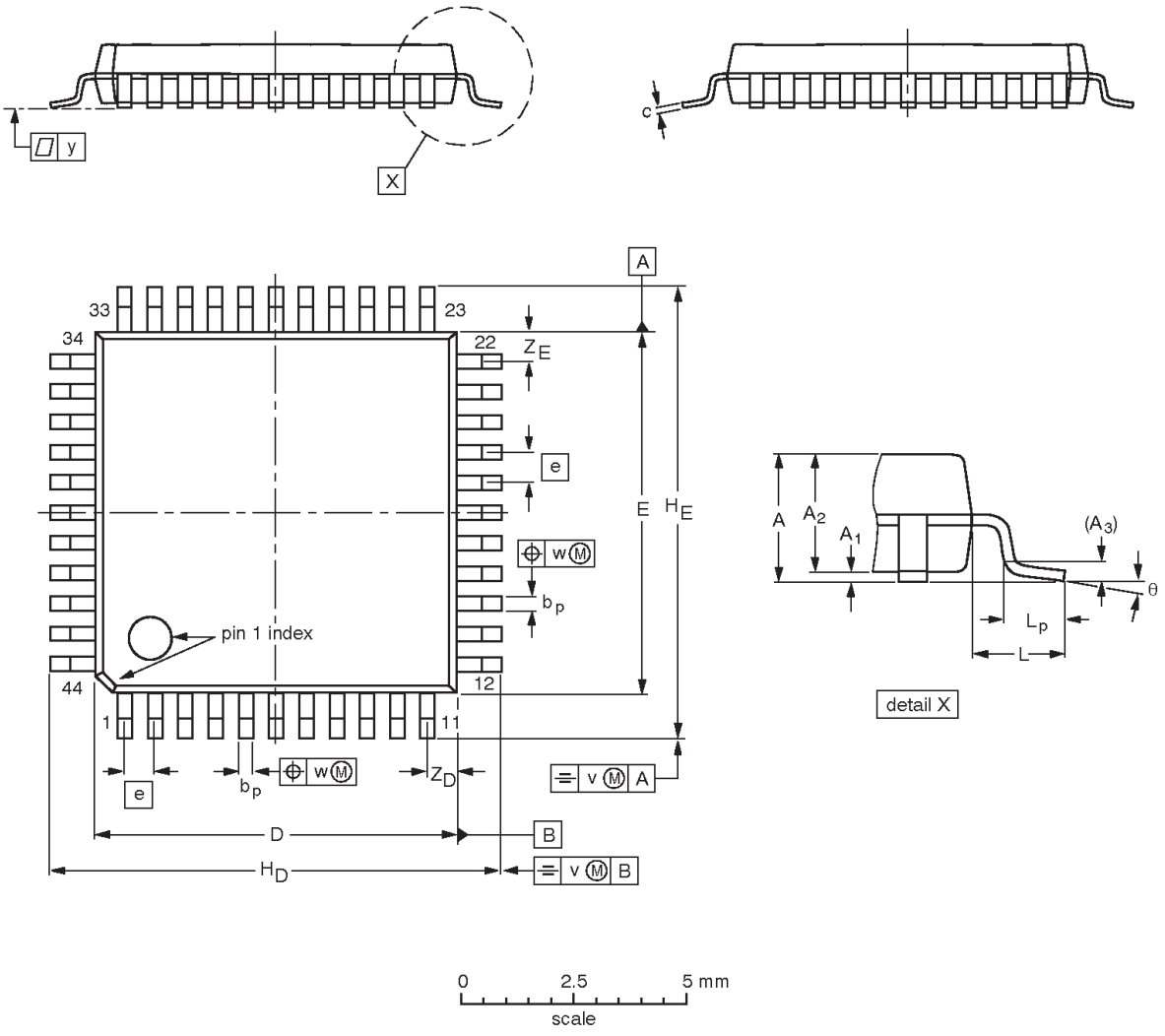


Figure 25. I_{CC} Test Condition, Power Down Mode
All other pins are disconnected. V_{CC} = 2 V to 5.5 V

QFP44: plastic quad flat package; 44 leads (lead length 1.3 mm); body 10 x 10 x 1.75 mm SOT307-2



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_D	H_E	L	L_p	v	w	y	$Z_D^{(1)}$	$Z_E^{(1)}$	θ
mm	2.10	0.25 0.05	1.85 1.65	0.25	0.40 0.20	0.25 0.14	10.1 9.9	10.1 9.9	0.8	12.9 12.3	12.9 12.3	1.3	0.95 0.55	0.15	0.15	0.1	1.2 0.8	1.2 0.8	10^o 0^o

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT307-2						~~95-02-04~~ 97-08-01

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

[1] Please consult the most recently issued datasheet before initiating or completing a design.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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